

Amendments to the Claims:

1. (currently amended) A method of separating a thin die from a support body of a semiconductor wafer, the thin die attached to the support body by an attachment mechanism that extends across an open trench in the wafer, the method comprising the steps of:

positioning a tip of a handler above the thin die, the tip having a passageway to a vacuum source;

positioning an ejection pin in a spaced apart relationship beneath the thin die;

moving the tip of the handler downward toward the thin die to push the thin die to

break the attachment mechanism from the support body;

clamping the thin die between the tip of the handler and the ejection pin; and

moving the ejection pin upward in the direction of the tip of the handler until the

thin die is extracted from the wafer;

lifting the tip of the handler and thin die away from the ejection pin;

positioning the tip of the handler and thin die above a surface that is a diaphragm

for measuring the pressure of a liquid;

moving the tip of the handler and thin die downward toward the surface; and

placing the thin die on the surface.

2. (original) The method of claim 1 wherein the attachment mechanism includes a plurality of tethers that extends between the thin die and the support body.

3. (original) The method of claim 1 wherein the tip of the handler is made of a flexible material.

4. (original) The method of claim 1 wherein the handler further has a spring and a rigid body portion, the spring configured to allow the tip of the handler to move in relation to the rigid body portion.

5. (original) The method of claim 1 further comprising the step of activating the vacuum source to provide a suction force through the passageway in the tip prior to the step of moving the tip of the handler downward toward the thin die.

6. (original) The method of claim 1 wherein the thin die remains clamped between the tip of the handler and the ejection pin during the step of moving the ejection pin upward in the direction of the tip of the handler.

7. (canceled)

8. (canceled)

9. (canceled)

10. (withdrawn) A method of separating a thin die from a support body of a semiconductor wafer, the thin die attached to the support body by a plurality of tethers that extend across an open trench in the wafer, the method comprising the steps of:

positioning a tip of a handler above the thin die, the tip having a passageway to a vacuum source;

activating the vacuum source to provide a suction force through the passageway of the tip;

positioning an ejection pin in a spaced apart relationship beneath the thin die;

moving the tip of the handler downward toward the thin die to break the plurality of tethers;

clamping the thin die between the tip of the handler and the ejection pin; and

moving the ejection pin upward in the direction of the tip of the handler until the thin die is extracted from the wafer.

11. (withdrawn) The method of claim 10 further comprising the step of positioning the wafer on a rigid backing having a hole, the hole positioned beneath the thin die.

12. (withdrawn) The method of claim 10 wherein the tip of the handler is made of a flexible material.

13. (withdrawn) The method of claim 10 wherein the handler further has a spring and a rigid body portion, the spring configured to allow the tip of the handler to move in relation to the rigid body portion.

14. (withdrawn) The method of claim 10 further comprising the step of lifting the tip of the handler and thin die away from the ejection pin.

15. (withdrawn) The method of claim 14 further comprising the steps of:
 - positioning the tip of the handler and thin die above a surface;
 - moving the tip of the handler and thin die downward toward the surface;
 - placing the thin die on the surface.
16. (withdrawn) The method of claim 15 wherein the surface is a diaphragm for measuring the pressure of a liquid.
17. (withdrawn) A method of separating a thin die from a support body of a semiconductor wafer, the thin die having an outer perimeter defined by an open trench in the wafer, the open trench positioned between the thin die and the support body of the wafer, the thin die attached to the support body by a plurality of tethers that extend across the open trench, the method comprising the steps of:
 - positioning the wafer on a rigid backing having a hole, the hole positioned beneath the thin die;
 - positioning an ejection pin within the hole of the backing and beneath the thin die;
 - positioning a tip of a handler above the thin die, the tip having a passageway to a vacuum source;
 - activating the vacuum source to provide a suction force through the passageway of the tip;
 - moving the tip of the handler downward toward the thin die to break the plurality of tethers; and

clamping the thin die between the tip of the handler and the ejection pin; and moving the ejection pin upward in the direction of the tip of the handler until the thin die is extracted from the wafer.

18. (withdrawn) The method of claim 17 wherein the tip of the handler is made of a flexible material.

19. (withdrawn) The method of claim 17 wherein the handler further has a spring and a rigid body portion, the spring configured to allow the tip of the handler to move in relation to the rigid body portion.

20. (withdrawn) The method of claim 17 further comprising the steps of:
positioning the tip of the handler and thin die above a surface;
moving the tip of the handler and thin die downward toward the surface;
placing the thin die on the surface.